

BACK GRINDING ADHESIVE SHEET, AND METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER

Abstract

Provided is a back grinding adhesive sheet which can adequately protect protrusions provided to a semiconductor wafer, and with which back grinding can be adequately performed. The present invention provides a back grinding adhesive sheet for a semiconductor wafer having protrusions, the back grinding adhesive sheet comprising a non-adhesive cushion layer, and an adhesive layer provided on the cushion layer. The adhesive layer has an opening with a smaller diameter than the diameter of the semiconductor wafer, and the outer edge of the semiconductor wafer is adhered to the adhesive layer such that the protrusions on the semiconductor wafer are positioned inside the opening. The protrusions are protected by the cushion layer when the semiconductor wafer is in the state of being adhered to the adhesive layer. The adhesive sheet satisfies at least one of the following conditions (1)-(2). (1) When the cushion layer is cut out using the dumbbell from JISZ1702 and is stretched 25% at a gauge length of 40mm and a tensile speed of 300mm/min, the tensile stress is 2-30N/10mm. (2) The cushion layer is formed from a thermoplastic resin that has a melt flow rate (JISK7210, 125°C/10.0kg load) of 0.2-30g/10min, and a melting point of 60-110°C.

[Figures 1A, 1B, 1C, 1D]